

Lead-Free Solder Wire

Model: PF606-R

Rev.2013/04/01 Ver.12-00

— Specification —

No.	Item	Specification	Standard
1	Appearance	Bright and shiny surface finishes.	
2	Alloy	Sn / Ag3.0 / Cu0.5 / X	JIS-Z-3282
3	Melting Point	Approx. 217~219°C	DSC
4	Flux Content	3.0 ± 1.0%	JIS-Z-3283
5	Halide Content	Under 0.5%	JIS-Z-3197
6	Gravity	7.4	
7	Spread ability	> 75%	JIS-Z-3197
8	Packaging	0.5, 1, 5, 10kg/Roll.	JIS-Z-3283
9	Diameters Tolerances	0.3~0.7 ± 0.05mm, 0.8~3.0 ± 0.1mm	

— Reliability Test —

No.	Test Item	Test Result	Test Method
1	Copper Mirror Test	PASS	IPC-TM-650, 2.3.32
2	Copper plate Corrosion	PASS	IPC-TM-650, 2.6.15
3	S.I.R Test	PASS $1 \times 10^{10} \Omega$ up	IPC-TM-650, 2.6.3.3
4	Electrochemical migration Test	PASS $1 \times 10^{10} \Omega$ up	IPC-TM-650, 2.6.14.1

— Alloy Composition —

Sn	Ag	Cu	Ni	Ge	Pb	Sb	Bi	Cd	Au	In	Al	As	Fe	Zn
REM.	2.8~ 3.2	0.3~ 0.7	0.001~ 0.01	0.001~ 0.01	0.05 Max	0.05 Max	0.10 Max	0.002 Max	0.05 Max	0.10 Max	0.001 Max	0.03 Max	0.02 Max	0.001 Max

Patent No.: Japanese Patent No. 3296289 U.S Patent No. 6179935B1. Germany Patent No.19816671C2. (wt %)

All alloy of SHENMAO' products were to conform to SONY Green Partner and comply RoHS requirement.



— Features and Storage Instructions —

1. Features

Excellent solder joint reliability. Superior joint strength. Excellent thermal & Mechanical fatigue resistance. Suitable for no-clean process.

2. Storage Instructions

Storage must be in a dry, non-corrosive and shine environment. Avoids the oxidant, the acid and the hydrogen peroxide. Shelf life is 2 years from date of manufacture.



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